

Text of Claims Currently Under Examination

1-21 canceled

22. (currently amended): A moisture curable hot melt adhesive composition prepared by reacting a polyisocyanate with a mixture comprising (i) a urethane diol and (ii) a polyether polyol or polyester diol or both, said urethane diol being the reaction product of a cyclic carbonate and a compound containing an amino group and a further group selected from the group consisting of amino groups and hydroxyl groups, which composition, in the presence of moisture, cures to an irreversible solid form.

23. (previously presented): The composition of claim 22 wherein the said compound is a diamine, an alkanolamine, an amine terminated polyamide or mixture thereof.

24. (previously presented): The composition of claim 23 wherein said compound is selected from the group consisting of ethylene diamine, 1,4 butane diamine, 1,6 hexane diamine, 2 methyl 1,5 pentane diamine, 2,2,4 trimethyl-1,6 hexane diamine, 2,4,4 trimethyl-1,6 hexane diamine, polyoxypropylene diamines, ethanolamine, propanolamine and mixtures thereof.

25. (previously presented): The composition of claim 22 wherein said cyclic carbonate is selected from the groups consisting of glycerol carbonate, ethylene carbonate, propylene carbonate and butylene carbonate.

26. (previously presented): The composition of claim 22 wherein said mixture further comprises a (meth)acrylic polymer, a thermoplastic polymer, a tackifying resin or a mixture thereof.

27. (previously presented): The composition of claim 22 which is in solid form.

28. (previously presented): The composition of claim 22 which is in liquid form.

29. (previously presented): The composition of claim 22 wherein the urethane diol is made in situ during the preparation of the polyurethane prepolymers.

30 (previously presented): The composition of claim 28 which has a melt viscosity suitable to enable application at a temperature of less than 100°C.

31. (previously presented): A method of bonding materials together which comprises applying the moisture curable hot melt adhesive composition of claim 22 in a liquid form to a first substrate, bringing a second substrate in contact with the composition applied to the first substrate, and subjecting the composition to conditions which will allow the compositions to cool and cure to an irreversible solid form, the conditions comprising moisture.

32. (previously presented): The method of claim 31 wherein the adhesive composition in liquid form is applied at a temperature of less than 100°C.

33. (previously presented): The method of claim 31 wherein the adhesive composition in liquid form is applied at a temperature of 90°C to 100°C.

34. (previously presented): An article of manufacture which comprises the composition of claim 22 which composition has been cured by exposure to moisture.

35. to 37. (canceled)